Real time degradation monitoring system for high power IGBT module under power cycling test

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Abstract

A “real time” monitoring system which enables to observe internal degradation process to failure of power semiconductors under power cycling test is proposed. The system was realized by combining a scanning acoustic tomography (SAT/SAM), power stress controlling, device cooling, water jet system and chip temperature monitoring. Two contradictory problems, namely, electrically wiring for power cycling and waterproof of device for SAT imaging were compatible with each other by experimental setup with an original water tank. Self-heating of power devices was supressed by controlling temperature of water which is couplant of ultrasonic wave for the SAT. A demonstration of this system was performed by using an IGBT module which maximum rating of collector current was 400 A (DC).

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1. Introduction

Wide area of power semiconductor applications promises huge volume manufacturing of them in the not-too-distant future. Downsizing of power semiconductors increases their productivity and enable such huge volume manufacturing. On the other hand, the downsizing increases power density of the devices and maximizes reliability risk of them. In this situation, failure mechanism based reliability assessment would be important to minimize reliability risk of power semiconductors. A “real time” monitoring of internal process to failure in power semiconductors under operating is a helpful tool for the failure mechanism based reliability assessment. It has significant advantages over the

Fig. 1. Real time degradation monitoring system for high power IGBT module.
conventional “post stress” failure analysis technique in capturing the real trigger point of the failure before the defects are propagated substantially large areas.

In this paper, a “real time” monitoring system which enables to observe internal degradation process to failure of power semiconductors under power cycling test. This system was designed for widely used high power IGBT modules which base plate substrate area is ~50 cm² and realized by combining a scanning acoustic tomography (SAT/SAM), power stress controlling, device cooling, water jet system and chip temperature monitoring.

2. Real time monitoring system Set-Up

The main components for the proposed system were a) inside imaging of DUT, 2) high power stress control, 3) device cooling and 4) chip temperature monitoring as shown Fig. 1, Fig. 2 and Table 1.

2.1. Scanning acoustic tomography (SAT)

The SAT was employed as an imaging tool for monitoring internal process to failure of device under test (DUT) as a movie. The SAT is widely used for the failure inspection of the power devices by means of non-destructive imaging [1-8]. Two contradictory problems, namely electrically wiring for power cycling test and waterproof of the module for SAT imaging, were compatible with each other by experimental setup with an original water tank shown in Fig. 3. The DUT was attached to the view window at the bottom of the water tank with a sealing sheet made of silicone rubber. Inside images of an IGBT module could be observed by the SAT with 50 MHz and 20 mm focal distance transducer through from the base plate substrate.

2.2. Power stress circuit

High power stress was applied to the DUT by a 16 kW DC power supply which controlled by a PC. A switching box shown in Fig. 4 was inserted between the output of power supply and DUT to separate them completely when the power stress was turn off. This switching box was also used for the chip temperature measurement.

<table>
<thead>
<tr>
<th>Function</th>
<th>Apparatus</th>
<th>Product Model</th>
</tr>
</thead>
<tbody>
<tr>
<td>Inside imaging of DUT</td>
<td>Scanning Acoustic Tomography</td>
<td>FineSAT FS100 III (Hitachi Power Solutions Co., LTD.)</td>
</tr>
<tr>
<td>High power stress</td>
<td>DC power supply</td>
<td>PAT30-532TM (KIKUSUI ELECTRONICS CORP.)</td>
</tr>
<tr>
<td>Stress control</td>
<td></td>
<td>LabView (National Instruments)</td>
</tr>
<tr>
<td>Device cooling</td>
<td>Water chiller</td>
<td>RKE1500B1-V-G2 (ORION MACHINERY Co., LTD.)</td>
</tr>
<tr>
<td>Radiator</td>
<td></td>
<td>HS-C100 (KAWASO TEXCEL)</td>
</tr>
<tr>
<td>Water jet</td>
<td>Water pump</td>
<td>LMB15107315 (Laing Thermotech)</td>
</tr>
<tr>
<td></td>
<td>Water jet nozzle</td>
<td>Own made</td>
</tr>
<tr>
<td>Temperature monitoring (Water and base plate)</td>
<td>Fiber optic temperature sensor</td>
<td>FOT-L-SD (FISO Technologies)</td>
</tr>
<tr>
<td></td>
<td>Controller</td>
<td>UMI8 (FISO Technologies)</td>
</tr>
<tr>
<td>Chip temperature monitoring</td>
<td>Switching box</td>
<td>Own made with GX16CEB &amp; BD9521 (GIGAVAC)</td>
</tr>
<tr>
<td></td>
<td>Voltage monitor</td>
<td>TDS2022 (Tektronix, Inc.)</td>
</tr>
<tr>
<td></td>
<td>Control program</td>
<td>LabView (National Instruments)</td>
</tr>
</tbody>
</table>
An appropriate cooling system was necessary for the real time observation of DUT especially for the SAT observation, because an abnormal temperature rise of couplant water results in degradation of SAT images [8]. The device temperature was controlled by the couplant water temperature for this system.

The water cooled by a chiller was lead to a radiator attached to the bottom of the water tank made of aluminium. The radiator cooled down the couplant water surrounding the DUT and maintained the temperature of its surface.

### 2.4. Water jet system

A local convection and formation of tiny bubbles on the observation surface caused by self-heating of DUT also degrade the SAT images [8]. These problems were solved by introducing water jet system which generates a high speed water flow along the scanning interface. The water flow suppresses the convection just beneath the transducer and pushes out the bubbles on the surface.

### 2.5. Chip temperature monitoring

The device cooling manner of this system using surrounded water is much different from that of actual power devices under operating. One typical parameter enabling to compare these power stress condition is the temperature swing $\Delta T_j$ is given by the temperature difference between maximal junction temperature $T_{\text{high}}$ at the end of the heating phase and the minimal junction temperature $T_{\text{low}}$ at the end of the cooling interval:

$$\Delta T_j = T_{\text{high}} - T_{\text{low}} \ [9,10]$$

Temperature sensitive parameters of device, such as on-state voltage drop at low current and threshold voltage in IGBT’s or the on-state voltage drop at low current in freewheeling diodes, are often utilized for measuring the $\Delta T_j$. The switching circuit between the power supply and DUT enables these different current polarity measurements.

### 2.6. GUI for the system control

These systems are controlled via GUI which consists of SAT Image Acquisition window and power stress control window (Fig. 5). SAT acquisition parameters such as gate of reflected echo from DUT are set in the SAT controller window and...
continuous scan image is displayed in the same window. The power stress parameters such as a load current, a power cycle time and a duration of the cycle, are set in the power stress controller window. Temperatures of the water and DUT surface, electric current and voltage are also monitored in this window. The power stress controller window is programmed with LabView.

3. Real time monitoring results

The demonstration was performed with an IGBT module which maximum rating of collector current was 400 A (DC). A constant gate-emitter voltage ($V_{GE}$) of 15 V was applied to only the high-side IGBT and the high-side emitter was connected to the earth. The load current to the collector was switched by DC power supply with a programmed sequence.

Figure 6 shows SAT images of the DUT obtained under the different load current. Four acquisition gates were configured from the base plate substrate to obtain SAT images of different interface region. It took 16 second to obtain one frame of the SAT image of 75 mm $\times$ 35 mm region with 500 $\mu$m resolution, therefore the load current sequence was configured 30 second turn-on and -off cycle. Comparing with the images under the load current was turn-on and turn-off, any remarkable image degradation has not been recognized even under the 200 A load current flow. This result is also confirmed by the fact that the quality of image is not differ between the biased high-side region and the low-side region under the 200 A load current flow. Some dark spots (pointed by black arrow in Fig. 6) of tiny bubble appeared on the image, but it is able to solve by optimizing the water jet system.

Temperatures of the water and DUT surface monitored under the load current of 50 A and 200 A is shown in Fig. 7. The temperature of surrounded water under the load current of 200 A was gradually elevated and finally settled at around 25 $^\circ$C. The base plate temperature indicated the same behaviour with a vibration in 5 $^\circ$C followed by the load sequence and finally saturated between 24 ~ 30 $^\circ$C. Although this temperature behaviour did not affect the SAT image in this demonstration, its influence could become obvious when the high power stress is applied. Furthermore, temperature variation in the DUT is complicated because heat condition of assemblies is not equal depending on its material or interface.

![Inside photograph of the IGBT module](image)

<table>
<thead>
<tr>
<th>Gate1</th>
<th>Gate2</th>
<th>Gate3</th>
<th>Gate4</th>
</tr>
</thead>
<tbody>
<tr>
<td>50 A</td>
<td>Turn off</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Turn on</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>200 A</td>
<td>Turn off</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Turn on</td>
<td></td>
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</tr>
</tbody>
</table>

Fig. 6. SAT images of the DUT obtained under the different load current. The biased high-side chip is observed in the right side region of each image. The inside photograph is upset the top and bottom to adjust to these SAT images observed from the base plate substrate. A rectangular shadow in the bottom center is a shadow of adhesive tape to settle the temperature sensor.
Acknowledgements

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References